Small production line

Line capacity: **30 000 CPH (Optimum*)**

Korean SMT Solutions – the best is available for you.

Stop choosing between the best and the affordable.

The equipment in the line is selected regarding the wide range of tasks of a beginner company or small own manufacturing.

The line equipment is maximally coordinated by specifications and abilities to consider it as a universal solution to assemble PCBs of various complexity.

The line is fully automatic from loading of PCBs up to output of assembled product. One or two operators are enough for such line with positive influence to the cost of the product.

The line works with any most frequently used SMD components – from small chip components 01005 up to big ICs 55 x 55 mm and 15mm height. Component mounting precision is ± 30µm (at 3 σ).

It corresponds to the best precision characteristics of up-to-date analogous equipment.

Possibility to prepare work program offline together with intelligent feeders and docking carts allows maximal preparation of a project before launching in the line.

Changeover of the line to a new project takes only several minutes. The line capacity could be increased in the future by upgrading with more efficient pick-and-place system. It provides a large reserve for further development of the initial manufacturing with minimal investments

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* The above production speed is based on the optimum. It differs depending on the customers’ production environment. For a more detailed line configuration, please contact our sales team.
Options list:

For SMD pick-and-place system:

- Feeder docking cart for quick changeover to a new product
- Offline programming software for faster creation of programs
- System of barcode reading from component reels for convenient work of electronic warehouse
- Electric reel tape feeders for tape 8 – 88 mm
- Smart feeder for auto loading/splicing SMD reels
- Stick feeder for 4 sticks for SOP, SOJ, QFP, PLCC, connector, etc
- Manual tray feeder for IC in JEDEC pallets
- Automatic tray feeder up to 48 JEDEC pallets with Non stop production changeover
- Flux Dipping Unit

For solder paste printer:

- Pneumatic support pins
- Automatic adding of solder paste
- Microclimate support system

For solder paste reflow oven:

- Thermal profiler to control temperature at PCB surface
- Possibility to combine chain and mesh conveyors for simultaneous work with PCBs of different width

Line specification:

- PCB size: from 50 x 40 mm up to 510 x 420 mm
- Speed (Optimum*): 30,000 CPH for chip components
- Components: from 01005 up to 55 x 55 mm (or 55 x 75 mm for oblong components), max. height of component 15 mm
- Quantity of 8 mm feeders: 120 ea.
- Component placing precision: ± 30 µm (at 3 σ)
- Solder paste application control: 2D vision system
- Oven: 7 heating zones, 1 cooling

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